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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Last Time Buy
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	CANbus, I ² C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	31
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	·
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/nuvoton-technology-corporation-america/nuc140le3cn

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2 FEATURES

The equipped features are dependent on the product line and their sub products.

2.1 NuMicro[™] NUC140 Features – Connectivity Line

- Core
 - ARM[®] Cortex[™]-M0 core runs up to 50 MHz
 - One 24-bit system timer
 - Supports low power sleep mode
 - Single-cycle 32-bit hardware multiplier
 - NVIC for the 32 interrupt inputs, each with 4-levels of priority
 - Serial Wire Debug supports with 2 watchpoints/4 breakpoints
- Build-in LDO for wide operating voltage ranges from 2.5 V to 5.5 V
- Flash Memory
 - 32K/64K/128K bytes Flash for program code
 - 4KB flash for ISP loader
 - Support In-system program (ISP) application code update
 - 512 byte page erase for flash
 - Configurable data flash address and size for 128KB system, fixed 4KB data flash for the 32KB and 64KB system
 - Support 2 wire ICP update through SWD/ICE interface
 - Support fast parallel programming mode by external programmer
- SRAM Memory
 - 4K/8K/16K bytes embedded SRAM
 - Support PDMA mode
- PDMA (Peripheral DMA)
 - Support 9 channels PDMA for automatic data transfer between SRAM and peripherals
- Clock Control
 - Flexible selection for different applications
 - Built-in 22.1184 MHz high speed OSC for system operation
 - Trimmed to \pm 1 % at +25 °C and V_{DD} = 5 V
 - Trimmed to \pm 3 % at -40 °C ~ +85 °C and V_{DD} = 2.5 V ~ 5.5 V
 - Built-in 10 KHz low speed OSC for Watchdog Timer and Wake-up operation
 - Support one PLL, up to 50 MHz, for high performance system operation
 - External 4~24 MHz high speed crystal input for USB and precise timing operation External 32.768 kHz low speed crystal input for RTC function and low power system operation

• GPIO

- Four I/O modes:
 - Quasi bi-direction
 - Push-Pull output
 - Open-Drain output
 - Input only with high impendence
- TTL/Schmitt trigger input selectable
- I/O pin can be configured as interrupt source with edge/level setting
- High driver and high sink IO mode support

3.2 Pin Configuration

3.2.1 NuMicro™ NUC140 Pin Diagram

3.2.1.1 NuMicro™ NUC140 LQFP 100 pin



Figure 3-2 NuMicro™ NUC140 LQFP 100-pin Pin Diagram

Publication Release Date: Jan. 2, 2012 Revision V3.02

NuMicro[™] NUC140 Data Sheet

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3.2.1.2 NuMicro™ NUC140 LQFP 64 pin





Publication Release Date: Jan. 2, 2012 Revision V3.02

5 FUNCTIONAL DESCRIPTION

5.1 ARM[®] Cortex[™]-M0 Core

The Cortex[™]-M0 processor is a configurable, multistage, 32-bit RISC processor. It has an AMBA AHB-Lite interface and includes an NVIC component. It also has optional hardware debug functionality. The processor can execute Thumb code and is compatible with other Cortex-M profile processor. The profile supports two modes -Thread mode and Handler mode. Handler mode is entered as a result of an exception. An exception return can only be issued in Handler mode. Thread mode is entered on Reset, and can be entered as a result of an exception return. Figure 5-1 shows the functional controller of processor.



Figure 5-1 Functional Controller Diagram

The implemented device provides:

- A low gate count processor that features:
 - The ARMv6-M Thumb® instruction set
 - Thumb-2 technology
 - ARMv6-M compliant 24-bit SysTick timer
 - A 32-bit hardware multiplier
 - The system interface supports little-endian data accesses
 - The ability to have deterministic, fixed-latency, interrupt handling
 - Load/store-multiples and multicycle-multiplies that can be abandoned and restarted to facilitate rapid interrupt handling
 - C Application Binary Interface compliant exception model. This is the ARMv6-M, C Application Binary Interface (C-ABI) compliant exception model that enables the use of pure C functions as interrupt handlers

5.2.3 System Power Distribution

In this chip, the power distribution is divided into three segments.

- Analog power from AV_{DD} and AV_{SS} provides the power for analog components operation.
- Digital power from V_{DD} and V_{SS} supplies the power to the internal regulator which provides a fixed 2.5 V power for digital operation and I/O pins.
- USB transceiver power from V_{BUS} offers the power for operating the USB transceiver.

The outputs of internal voltage regulators, LDO and V_{DD33}, require an external capacitor which should be located close to the corresponding pin. Analog power (AV_{DD}) should be the same voltage level of the digital power (V_{DD}). Figure 5-2 shows the power distribution of NuMicroTM NUC140.



Figure 5-2 NuMicro™ NUC140 Power Distribution Diagram

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5.5 General Purpose I/O (GPIO)

5.5.1 Overview

NuMicro™ NUC130/NUC140 has up to 80 General Purpose I/O pins can be shared with other function pins; it depends on the chip configuration. These 80 pins are arranged in 5 ports named with GPIOA, GPIOB, GPIOC, GPIOD and GPIOE. Each port equips maximum 16 pins. Each one of the 80 pins is independent and has the corresponding register bits to control the pin mode function and data.

The I/O type of each of I/O pins can be configured by software individually as input, output, opendrain or guasi-bidirectional mode. After reset, the I/O type of all pins stay in guasi-bidirectional mode and port data register GPIOx_DOUT[15:0] resets to 0x0000_FFFF. Each I/O pin equips a very weakly individual pull-up resistor which is about 110 K Ω ~300 K Ω for V_{DD} is from 5.0 V to 2.5 V.

5.5.2 Features

- Four I/O modes:
 - Quasi bi-direction
 - Push-Pull output
 - **Open-Drain output**
 - Input only with high impendence
- TTL/Schmitt trigger input selectable
- I/O pin can be configured as interrupt source with edge/level setting
- High driver and high sink IO mode support



5.6.2 Features

The I²C bus uses two wires (SDA and SCL) to transfer information between devices connected to the bus. The main features of the bus are:

- Master/Slave mode
- Bidirectional data transfer between masters and slaves
- Multi-master bus (no central master)
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer
- Built-in a 14-bit time-out counter will request the I²C interrupt if the I²C bus hangs up and timer-out counter overflows.
- External pull-up are needed for high output
- Programmable clocks allow versatile rate control
- Supports 7-bit addressing mode
- I²C-bus controllers support multiple address recognition (Four slave address with mask option)



PIIR to get interrupt source and Read CRLRx/CFLRx(x=0~3) to get capture value and finally write 1 to clear PIIR to zero. If interrupt latency will take time T0 to finish, the capture signal mustn't transition during this interval (T0). In this case, the maximum capture frequency will be 1/T0. For example:

HCLK = 50 MHz, PWM_CLK = 25 MHz, Interrupt latency is 900 ns

So the maximum capture frequency will is 1/900ns ≈ 1000 kHz

5.7.2 Features

5.7.2.1 PWM function features:

- PWM group has two PWM generators. Each PWM generator supports one 8-bit prescaler, one clock divider, two PWM-timers (down counter), one dead-zone generator and two PWM outputs.
- Up to 16-bit resolution
- PWM Interrupt request synchronized with PWM period
- One-shot or Auto-reload mode PWM
- Up to 2 PWM group (PWMA/PWMB) to support 8 PWM channels or 4 PWM paired channels

5.7.2.2 Capture Function Features:

- Timing control logic shared with PWM Generators
- Support 8 Capture input channels shared with 8 PWM output channels
- Each channel supports one rising latch register (CRLR), one falling latch register (CFLR) and Capture interrupt flag (CAPIFx)



5.8 Real Time Clock (RTC)

5.8.1 Overview

Real Time Clock (RTC) controller provides user the real time and calendar message. The clock source of RTC is from an external 32.768 kHz low speed crystal connected at pins X321 and X32O (reference to pin descriptions) or from an external 32.768 kHz low speed oscillator output fed at pin X32I. The RTC controller provides the time message (second, minute, hour) in Time Loading Register (TLR) as well as calendar message (day, month, year) in Calendar Loading Register (CLR). The data message is expressed in BCD format. It also offers alarm function that user can preset the alarm time in Time Alarm Register (TAR) and alarm calendar in Calendar Alarm Register (CAR).

The RTC controller supports periodic Time Tick and Alarm Match interrupts. The periodic interrupt has 8 period options 1/128, 1/64, 1/32, 1/16, 1/8, 1/4, 1/2 and 1 second which are selected by TTR (TTR[2:0]). When RTC counter in TLR and CLR is equal to alarm setting time registers TAR and CAR, the alarm interrupt flag (RIIR.AIF) is set and the alarm interrupt is requested if the alarm interrupt is enabled (RIER.AIER=1). Both RTC Time Tick and Alarm Match can cause chip wake-up from power down mode if wake-up function is enabled (TWKE (TTR[3])=1).

5.8.2 Features

- There is a time counter (second, minute, hour) and calendar counter (day, month, year) for user to check the time
- Alarm register (second, minute, hour, day, month, year)
- 12-hour or 24-hour mode is selectable
- Leap year compensation automatically
- Day of week counter
- Frequency compensate register (FCR)
- All time and calendar message is expressed in BCD code
- Support periodic time tick interrupt with 8 period options 1/128, 1/64, 1/32, 1/16, 1/8, 1/4, 1/2 and 1 second
- Support RTC Time Tick and Alarm Match interrupt
- Support wake-up chip from power down mode

5.14 PS/2 Device Controller (PS2D)

5.14.1 Overview

PS/2 device controller provides basic timing control for PS/2 communication. All communication between the device and the host is managed through the CLK and DATA pins. Unlike PS/2 keyboard or mouse device controller, the received/transmit code needs to be translated as meaningful code by firmware. The device controller generates the CLK signal after receiving a request to send, but host has ultimate control over communication. DATA sent from the host to the device is read on the rising edge and DATA sent from device to the host is change after rising edge. A 16 bytes FIFO is used to reduce CPU intervention. S/W can select 1 to 16 bytes for a continuous transmission.

5.14.2 Features

- Host communication inhibit and request to send detection
- Reception frame error detection
- Programmable 1 to 16 bytes transmit buffer to reduce CPU intervention
- Double buffer for data reception
- S/W override bus



5.18 PDMA Controller (PDMA)

5.18.1 Overview

NuMicro[™] NUC130/NUC140 contains a peripheral direct memory access (PDMA) controller that transfers data to and from memory or transfer data to and from APB devices. The PDMA has nine channels of DMA (Peripheral-to-Memory or Memory-to-Peripheral or Memory-to-Memory). For each PDMA channel (PDMA CH0~CH8), there is one word buffer as transfer buffer between the Peripherals APB devices and Memory.

Software can stop the PDMA operation by disable PDMA [PDMACEN]. The CPU can recognize the completion of a PDMA operation by software polling or when it receives an internal PDMA interrupt. The PDMA controller can increase source or destination address or fixed them as well.

Notice: The partial of NuMicro[™] NUC130/NUC140 only has 1 PDMA channel (channel 0).

5.18.2 Features

- Support nine DMA channels. Each channel can support a unidirectional transfer
- AMBA AHB master/slave interface compatible, for data transfer and register read/write
- Support source and destination address increased mode or fixed mode
- Hardware channel priority. DMA channel 0 has the highest priority and channel 8 has the lowest priority



5.19 External Bus Interface (EBI)

5.19.1 Overview

The NuMicro[™] NUC130/NUC140 LQFP-64 and LQFP-100 package equips an external bus interface (EBI) for external device used.

To save the connections between external device and this chip, EBI support address bus and data bus multiplex mode. And, address latch enable (ALE) signal supported differentiate the address and data cycle.

5.19.2 Features

External Bus Interface has the following functions:

- External devices with max. 64K-byte size (8-bit data width)/128K-byte (16-bit data width) supported
- Variable external bus base clock (MCLK) supported
- 8-bit or 16-bit data width supported
- Variable data access time (tACC), address latch enable time (tALE) and address hold time (tAHD) supported
- Address bus and data bus multiplex mode supported to save the address pins
- Configurable idle cycle supported for different access condition: Write command finish (W2X), Read-to-Read (R2R)



7.3 AC Electrical Characteristics

7.3.1 External 4~24 MHz High Speed Oscillator



Note: Duty cycle is 50%.

SYMBOL	PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
t _{CHCX}	Clock High Time		20	3	20	nS
t _{CLCX}	Clock Low Time		20	-	Ya.	nS
t _{CLCH}	Clock Rise Time		-	-	10	nS
t _{CHCL}	Clock Fall Time		-	-	10	nS

7.3.2 External 4~24 MHz High Speed Crystal

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Input clock frequency	External crystal	4	12	24	MHz
Temperature	-	-40	-	85	°C
V _{DD}	-	2.5	5	5.5	V
Operating current	12 MHz@ V _{DD} = 5V	-	1	-	mA

7.3.2.1 Typical Crystal Application Circuits

CRYSTAL	C1	C2	R
4 MHz ~ 24 MHz	without	without	without



Specification of Low Voltage Reset 7.4.3

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Operation voltage	Ser all and a series of the se	1.7	-	5.5	V
Quiescent current	V _{DD} =5.5 V	-	-	5	uA
Temperature		-40	25	85	°C
	Temperature=25℃	1.7	2.0	2.3	V
Threshold voltage	Temperature=-40℃	Sil	2.4	-	V
	Temperature=85℃	100	1.6	N	V
Hysteresis	-	0	0	0	V

7.4.4 Specification of Brown-Out Detector

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Operation voltage	-	2.5	-	5.5	V
Quiescent current	AV _{DD} =5.5 V	-	-	125	μA
Temperature	-	-40	25	85	°C
	BOV_VL[1:0]=11	4.3	4.5	4.7	V
Brown-out voltage	BOV_VL [1:0]=10	3.6	3.8	4.0	V
Brown-out voitage	BOV_VL [1:0]=01	2.6	2.7	2.8	V
	BOV_VL [1:0]=00	2.1	2.2	2.3	V
Hysteresis	-	30	-	150	mV

7.4.5 Specification of Power-On Reset (5 V)

PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
Temperature	-	-40	25	85	°C
Reset voltage	V+	-	2	-	V
Quiescent current	Vin>reset voltage	-	1	-	nA
States of the second second	Publication - 67 -	n Release	e Date: J Rev	an. 2, 20 ision V3.	12 02

7.4.6 Specification of Temperature Sensor

PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply voltage ^[1]	gr the	2.5	-	5.5	V
Temperature		-40	-	125	°C
Current consumption		6.4	-	10.5	uA
Gain	No. of the second se	5.9	-1.76		mV/°C
Offset	Temp=0 ℃	S.	720		mV

Note: Internal operation voltage comes from LDO.

7.4.7 Specification of Comparator

	PARAMETER	CONDITION	MIN.	TYP.	MAX.	UNIT
	Temperature	-	-40	25	85	°C
	V _{DD}	-	2.4	3	5.5	V
	V _{DD} current	20 uA@V _{DD} =3 V	-	20	40	uA
	Input offset voltage	-	-	5	15	mV
	Output swing	-	0.1	-	V _{DD} -0.1	V
	Input common mode range	-	0.1	-	V _{DD} -1.2	V
	DC gain	-	-	70	-	dB
	Propagation delay	@VCM=1.2 V and VDIFF=0.1 V	-	200	-	ns
		20 mV@VCM=1 V				
		50 mV@VCM=0.1 V				
	Comparison voltage	50 mV@VCM=V _{DD} -1.2	10	20	-	mV
	the second se	@10 mV for non- hysteresis				
	S. A.W.	One bit control				
	Hysteresis	W/O and W. hysteresis	-	±10	-	mV
	C. Vr	@VCM=0.4 V ~ V _{DD} -1.2 V				
	Wake un time	@CINP=1.3 V		_	2	116
	wake-up une	CINN=1.2 V	-	-	2	us

7.4.8 Specification of USB PHY

7.4.8.1 USB DC Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{IH}	Input high (driven)	(B) :	2.0			V
VIL	Input low	No.	X		0.8	V
V _{DI}	Differential input sensitivity	PADP-PADM	0.2	1		V
V _{CM}	Differential common-mode range	Includes V_{DI} range	0.8	20	2.5	V
V _{SE}	Single-ended receiver threshold		0.8	SA	2.0	V
	Receiver hysteresis			200	2.6	mV
V _{OL}	Output low (driven)		0	9	0.3	V
V _{OH}	Output high (driven)		2.8		3.6	V
V _{CRS}	Output signal cross voltage		1.3		2.0	V
R _{PU}	Pull-up resistor		1.425		1.575	kΩ
V _{TRM}	Termination Voltage for upstream port pull up (RPU)		3.0		3.6	V
Z _{DRV}	Driver output resistance	Steady state drive*		10		Ω
C _{IN}	Transceiver capacitance	Pin to GND			20	pF

*Driver output resistance doesn't include series resistor resistance.

7.4.8.2 USB Full-Speed Driver Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
T _{FR}	Rise Time	CL=50p	4		20	ns
T _{FF}	Fall Time	C∟=50p	4		20	ns
T _{FRFF}	Rise and fall time matching	T _{FRFF} =T _{FR} /T _{FF}	90		111.11	%

7.4.8.3 USB Power Dissipation

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
IVDDREG	V _{DDD} and V _{DDREG} Supply Current (Steady State)	Standby		50		uA
(Full Speed)		Input mode				uA
		Output mode				uA

7.5	Flash	DC	Electrical	Characteristics

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
N _{endu}	Endurance	The second se	10000			cycles ^[1]
T _{ret}	Retention time	Temp=25 ℃	100			year
T _{erase}	Page erase time	×.	20		40	ms
T _{mass}	Mass erase time	1	40	50	60	ms
T _{prog}	Program time		35	40	55	us
V _{dd}	Supply voltage		2.25	2.5	2.75	V ^[2]
I _{dd1}	Read current		0	°S	14	mA
I _{dd2}	Program/Erase current			N	7	mA
I _{pd}	Power down current				10	uA

1. Number of program/erase cycles.

2. V_{dd} is source from chip LDO output voltage.

3. This table is guaranteed by design, not test in production.



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SPI Dynamic Characteristics 7.6

8 PACKAGE DIMENSIONS

8.1 100L LQFP (14x14x1.4 mm footprint 2.0mm)

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